

DC Brushless Motor Drivers for Fans

Standard Single-phase Full wave Fan Motor Driver

BD6981FVM
Description

This is the summary of application for BD6981FVM. BD6981FVM can drive FAN motor silently by BTL soft switching.

Features

- Small package (MSOP8)
- BTL soft switching drive
- Constant voltage output for hall element
- Lock protection and auto restart (without external capacitor)
- Rotating speed pulse signal (FG) output

Applications

- PC, PC peripheral component (Power supply, VGA card, case FAN etc.)
- BD player, Projector etc.

Package
 MSOP8

 W(Typ) x D(Typ) x H(Max)
 2.90mm x 4.00mm x 0.90mm

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V _{CC}	18	V
Power Dissipation	P _d	0.58 ^(Note 1)	W
Operating Temperature	T _{opr}	-40 to +105	°C
Storage Temperature	T _{stg}	-55 to +150	°C
Junction Temperature	T _{jmax}	150	°C
Output Voltage	V _{OMAX}	18	V
Output Current	I _{OMAX}	800 ^(Note 2)	mA
Hall Input Voltage	V _H	7	V
FG Signal Output Voltage	V _{FG}	18	V
FG Signal Output Current	I _{FG}	10	mA
HB Output Current	I _{HB}	10	mA

(Note 1) Reduce by 4.68mW/°C over 25°C. (On 70.0mmx70.0mmx1.6mm glass epoxy board)

(Note 2) This value is not to exceed P_d.

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Limit	Unit
Operating Supply Voltage Range	V_{CC}	2.8 to 16	V
Hall Input Voltage Range	V_H	0.4 to $V_{CC}/4$	V

Electrical Characteristics (Unless otherwise specified $T_a=25^{\circ}\text{C}$, $V_{CC}=12\text{V}$)

Parameter	Symbol	Limit			Unit	Conditions	Characteristics
		Min.	Typ.	Max.			
Circuit Current	I_{CC}	1.5	4	8	mA		Figure 1
Hall Bias Voltage	V_{HB}	1.1	1.2	1.3	V	$I_{HB}=-3\text{mA}$	Figure 2,3
Hall Input Offset	V_{OFS}	0	-	± 6	mV		-
Input-output Gain	G_{IO}	53	55	57	dB		-
Output Voltage	V_O	0.20	0.45	0.70	V	$I_O=200\text{mA}$ Upper and Lower total	Figure 4 to 7
FG Hysteresis Voltage	V_{HYS}	± 5	± 10	± 15	mV		Figure 8
FG Low Voltage	V_{FGL}	-	0.2	0.4	V	$I_{FG}=5\text{mA}$	Figure 9,10
FG Leak Current	I_{FGL}	0	-	5	μA	$V_{FG}=18\text{V}$	-
Lock Detection ON Time	t_{ON}	0.35	0.50	0.65	s		Figure 11
Lock Detection OFF Time	t_{OFF}	2.0	3.0	4.0	s		Figure 12
Lock Detection Time Ratio	r_{LD}	-	6	-	-	$r_{LD} = t_{OFF} / t_{ON}$	-

Truth Table

H+	H-	OUT1	OUT2	FG
H	L	H	L	H(Output Tr : OFF)
L	H	L	H	L(Output Tr : ON)

Reference Data

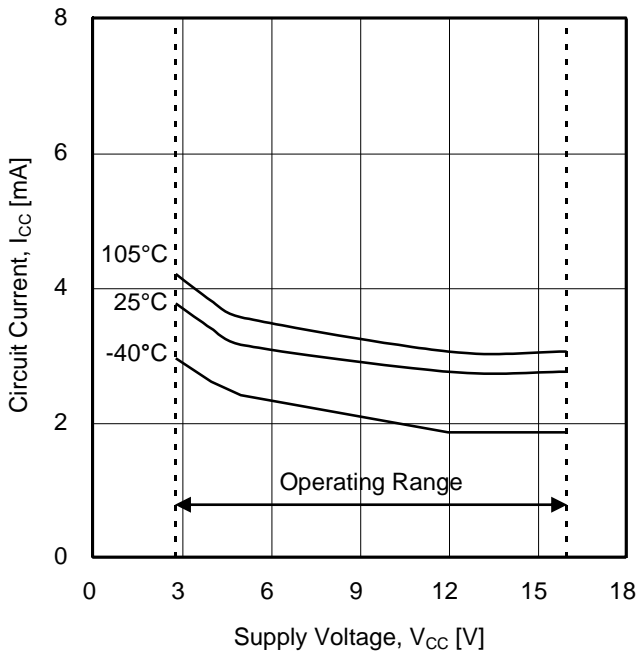


Figure 1. Circuit Current

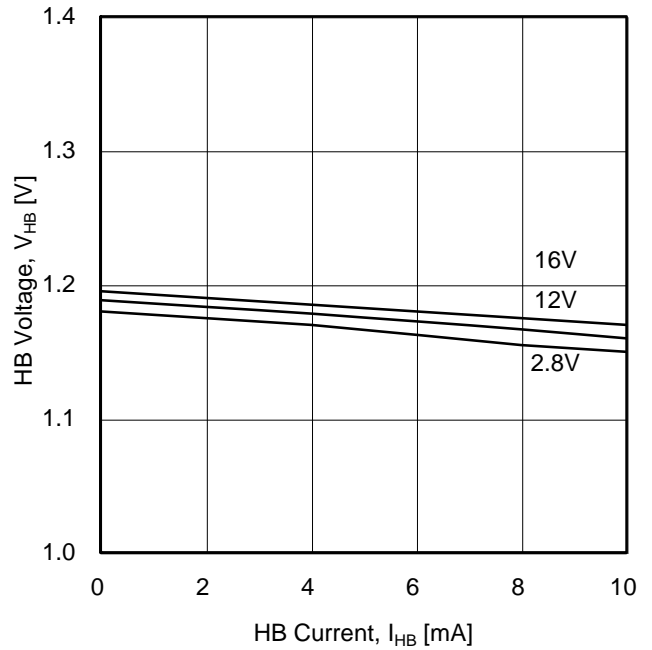


Figure 2. Hall Bias voltage (Voltage characteristics)

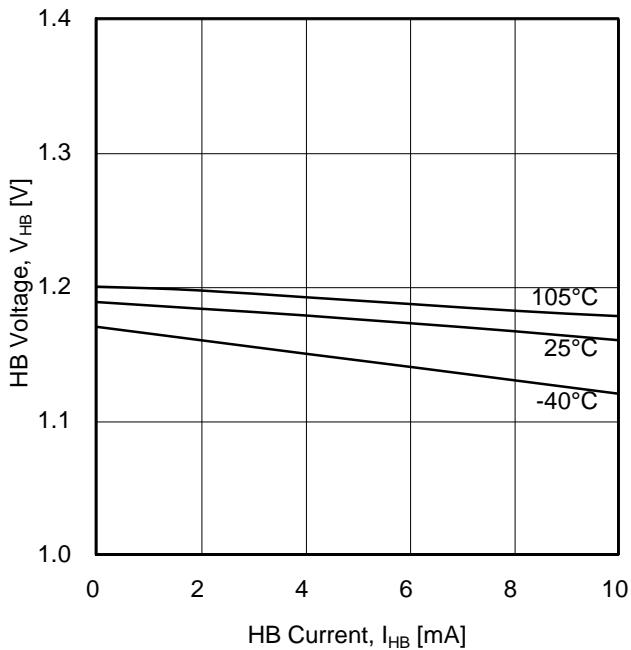


Figure 3. Hall Bias Voltage (Temperature Characteristics)

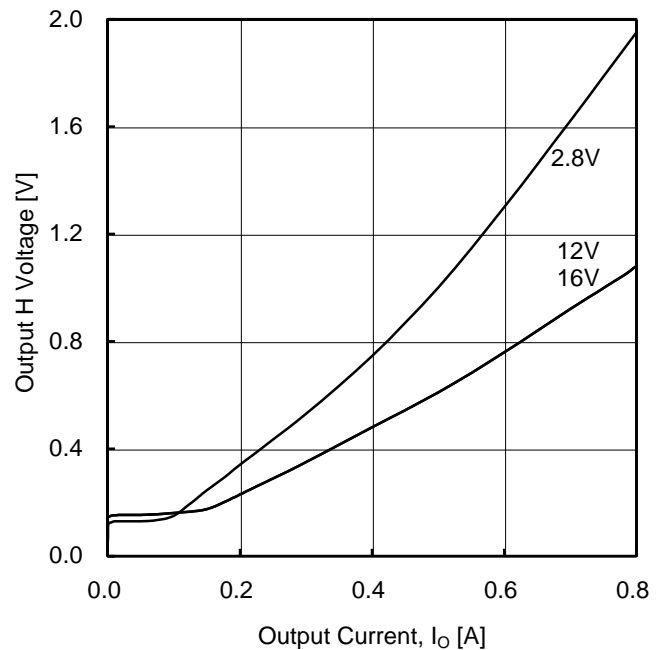


Figure 4. Output H Voltage (Voltage Characteristics)

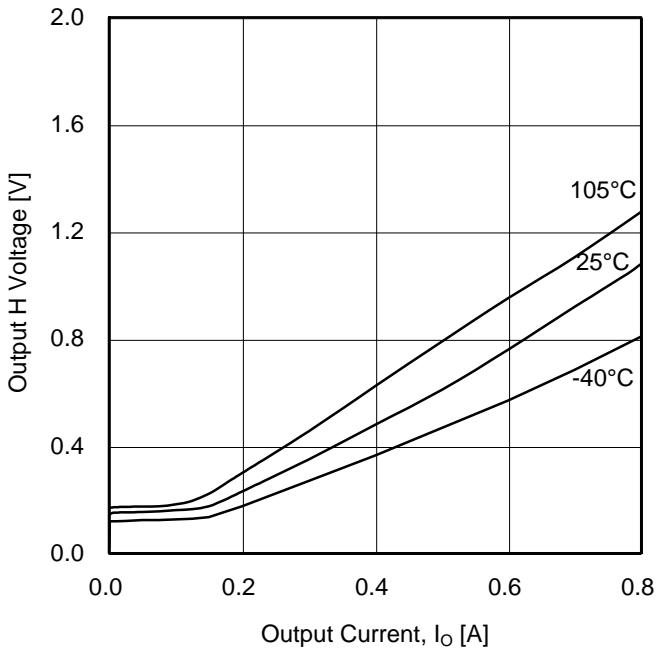


Figure 5. Output H Voltage (Temperature Characteristics)

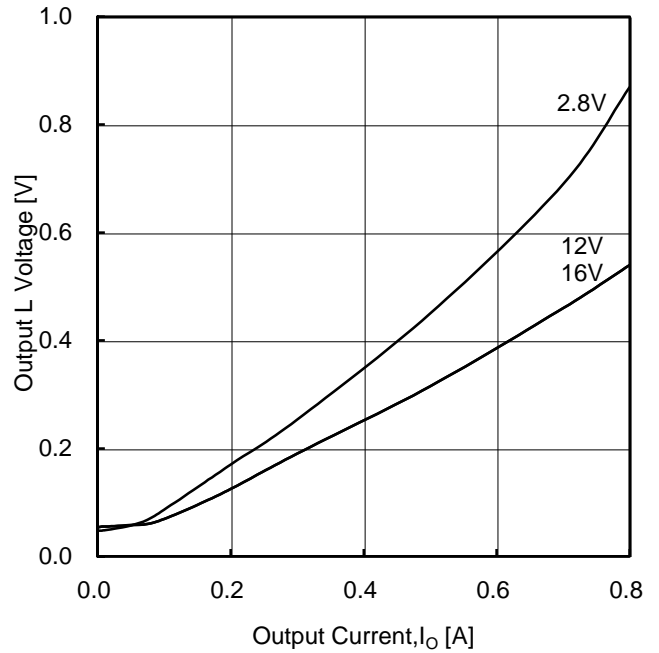


Figure 6. Output L Voltage (Voltage Characteristics)

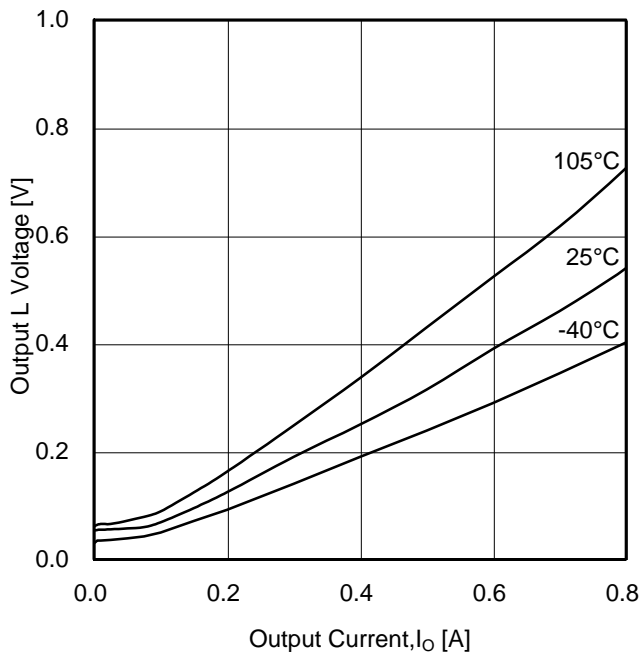


Figure 7. Output L Voltage (Temperature Characteristics)

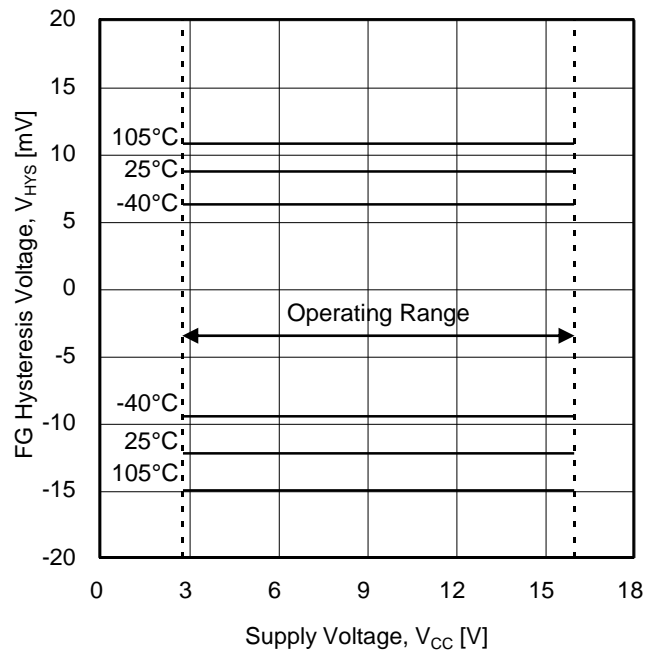


Figure 8. FG Hysteresis Voltage

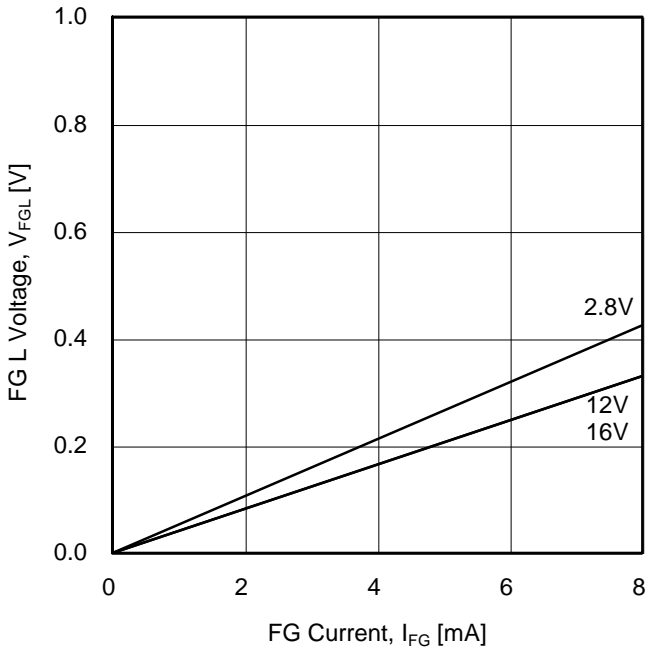


Figure 9. FG Output Voltage (Voltage Characteristics)

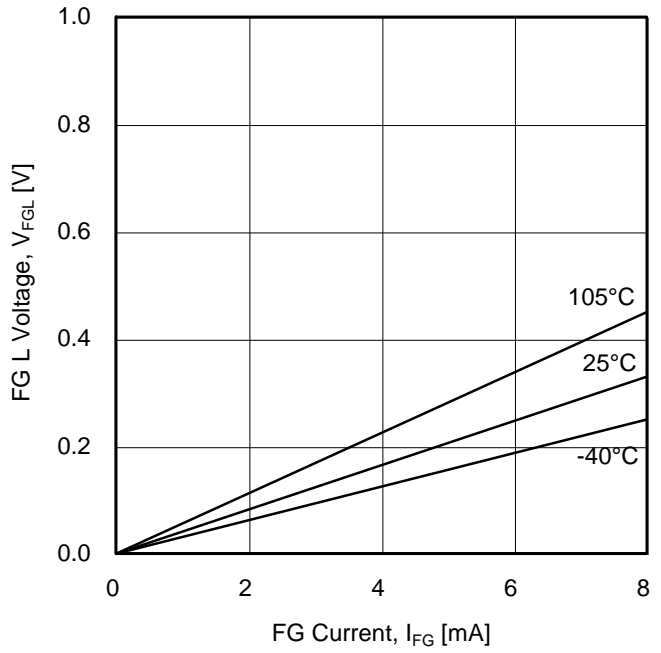


Figure 10. FG Output Voltage (Temperature Characteristics)

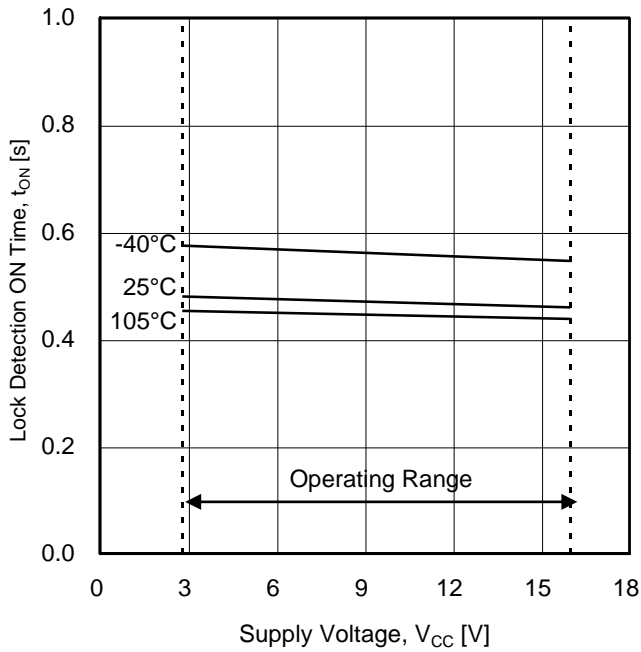


Figure 11. Lock Detection ON Time

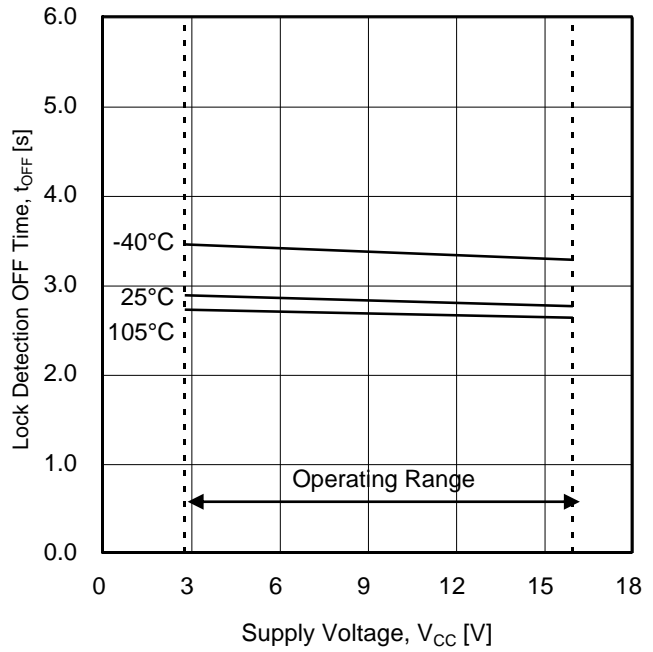
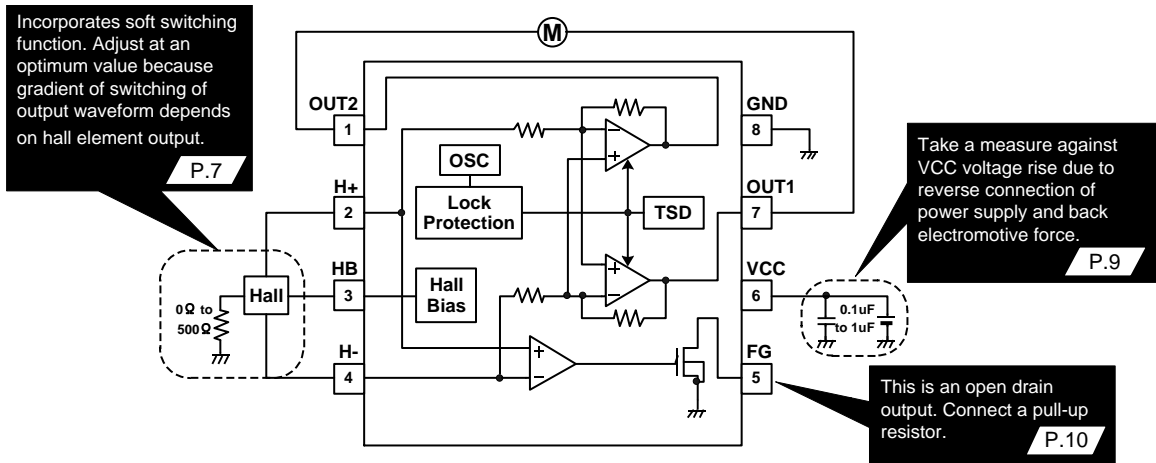


Figure 12. Lock Detection OFF Time

Block Diagram, Application Circuit and Pin Assignment



OSC : Internal reference oscillation circuit
 TSD : Thermal shut down(heat rejection circuit)

Pin Description

Pin No.	Pin Name	Function
1	OUT2	Motor output 2
2	H+	Hall input +
3	HB	Constant voltage output for hall element
4	H-	Hall input -
5	FG	Rotational speed pulse output
6	VCC	Power supply pin
7	OUT1	Motor output 1
8	GND	GND

Description of Operations

1) Lock Protection and Automatic Restart

Motor rotation is detected by hall signal. Lock detection ON time (t_{ON}) and lock detection OFF time (t_{OFF}) are set by the digital counter based on internal oscillator. Therefore the ratio of ON/OFF time is always constant. Timing chart is shown in Figure 13.

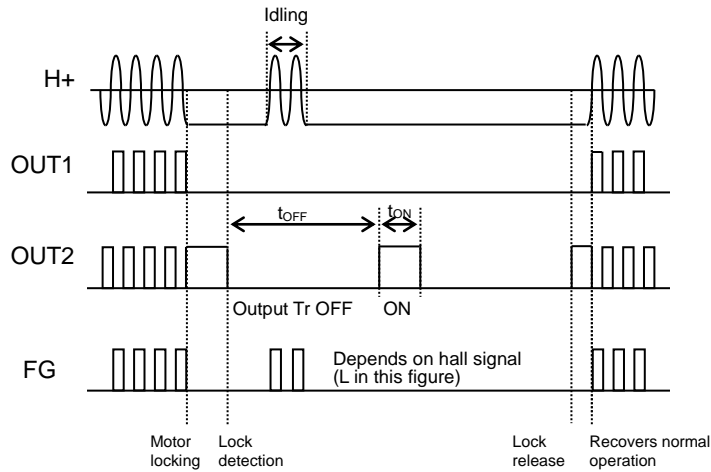


Figure 13. Lock Protection Timing Chart

2) Soft Switching (silent drive setting)

Input signal to hall amplifier is amplified to produce an output signal. When the hall element output signal is small, the gradient of switching of output waveform is gentle. When it is large, the gradient of switching of output waveform is steep. Gain of 55dB (560 times) is provided between input and output, therefore enter an appropriate hall element output to IC where output waveform swings sufficiently.

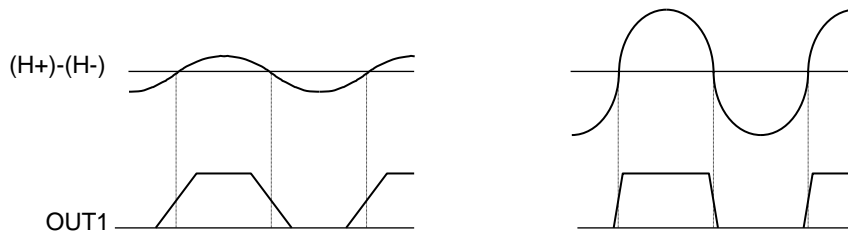


Figure 14. Relation between Hall Element Output Amplitude and Output Waveform

3) Hall Input Setting

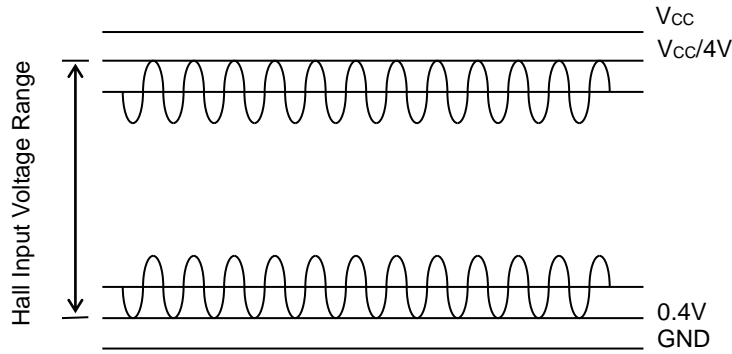


Figure 15. Hall Input Voltage Range

Adjust the value of R1 in Figure 16 so that the input voltage of a hall signal is input in "Hall Input Voltage Range" including signal amplitude.

In order to detect rotation of a motor, the amplitude of hall signal more than "FG hysteresis voltage" is required. Please input the hall signal of at least 30mVpp.

○Reducing the Noise of Hall Signal

Hall element may be affected by V_{CC} noise or the like depending on the wiring pattern of board. In this case, place a capacitor like C1 in Figure 16. In addition, when wiring from the hall element output to IC hall input is long, noise may be loaded on wiring. In this case, place a capacitor like C2 in Figure 16.

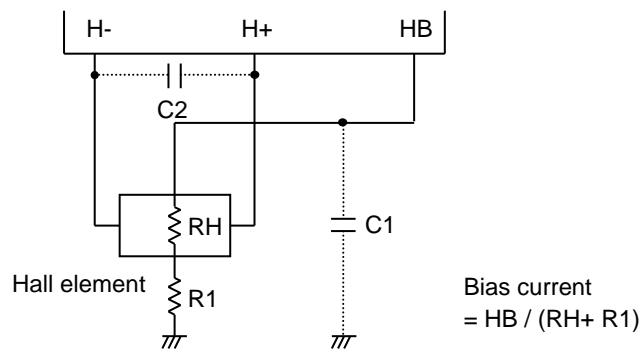
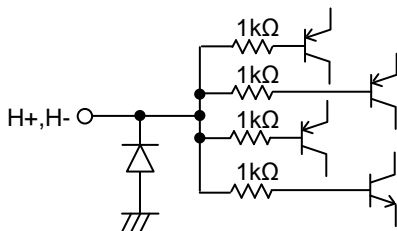


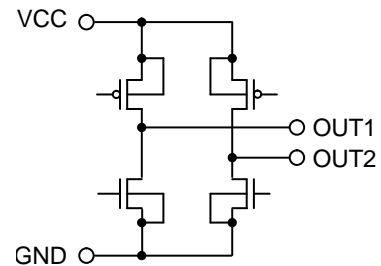
Figure 16. Application near of Hall Signal

Equivalent Circuit

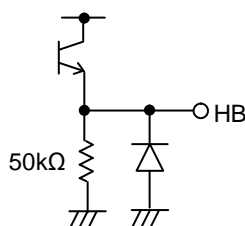
1) Hall Input



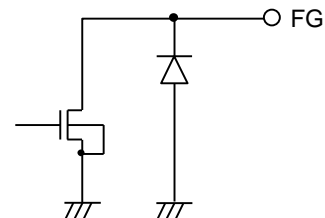
2) Motor Output



3) HB Output



4) FG Output



Safety Measure

1) Reverse Connection Protection Diode

Reverse connection of power results in IC destruction as shown in Figure 17. When reverse connection is possible, reverse connection protection diode must be added between power supply and VCC.

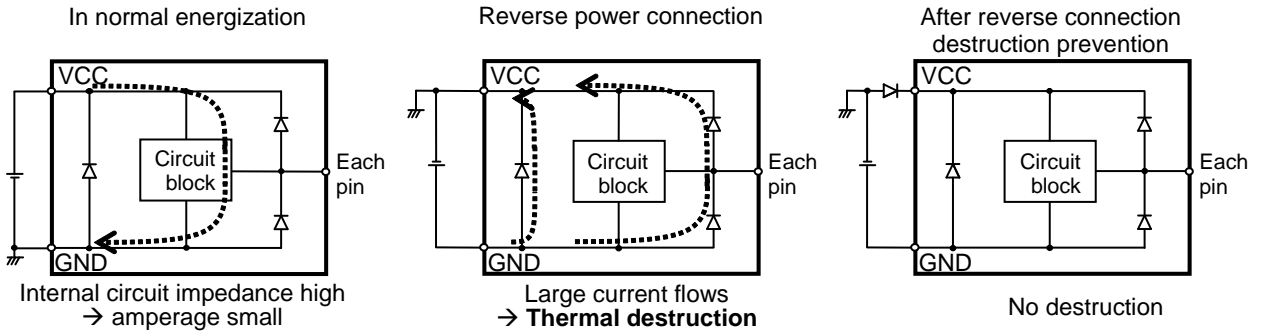


Figure 17. Flow of Current when Power is Connected Reverse

2) Measure against VCC Voltage Rise by Back Electromotive Force

Back electromotive force (Back EMF) generates regenerative current to power supply. However, when reverse connection protection diode is connected, VCC voltage rises because the diode prevents current flow to power supply.

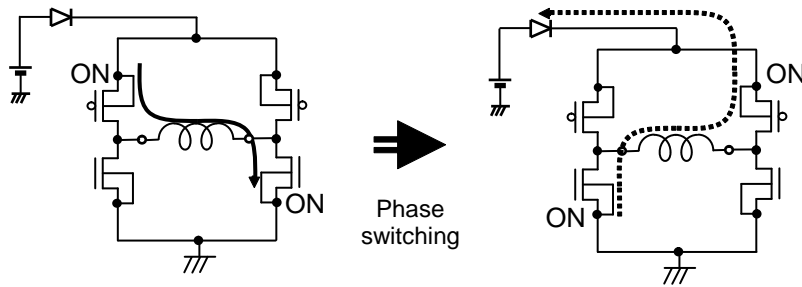


Figure 18. VCC Voltage Rise by Back Electromotive Force

When the absolute maximum rated voltage may be exceeded due to voltage rise by back electromotive force, place (A) Capacitor or (B) Zener diode between VCC and GND. It necessary, add both (C).

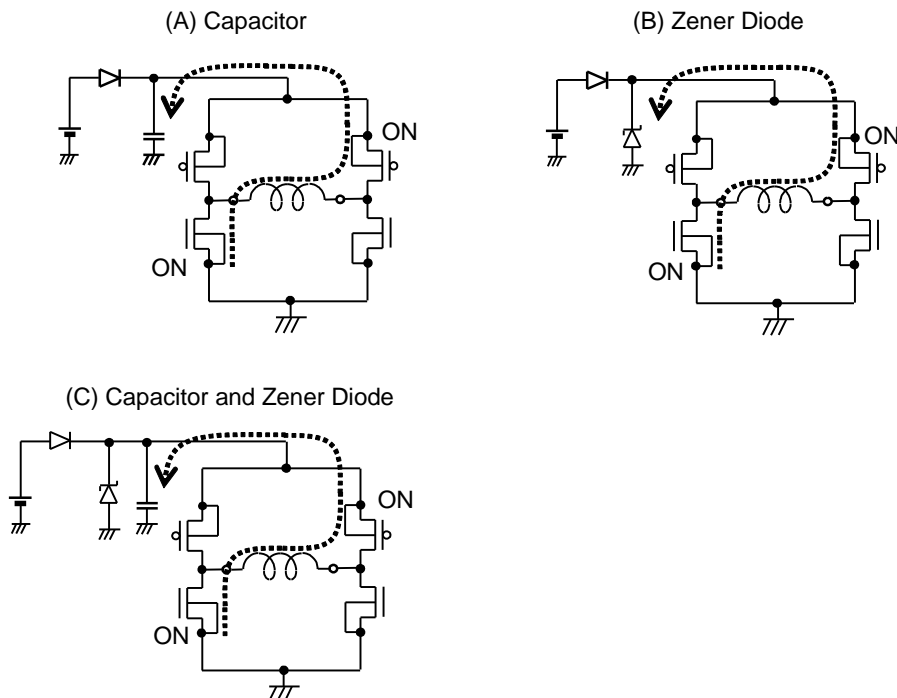


Figure 19. Measure against VCC Voltage Rise

3) Problem of GND Line PWM Switching

Do not perform PWM switching of GND line because GND potential cannot be kept to a minimum.

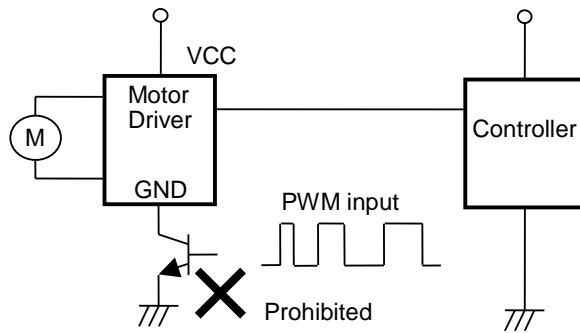


Figure 20. GND Line PWM Switching Prohibited

4) FG Output

FG output is an open drain and requires pull-up resistor. The IC can be protected by adding resistor R1. An excess of absolute maximum rating, when FG output pin is directly connected to power supply, could damage the IC.

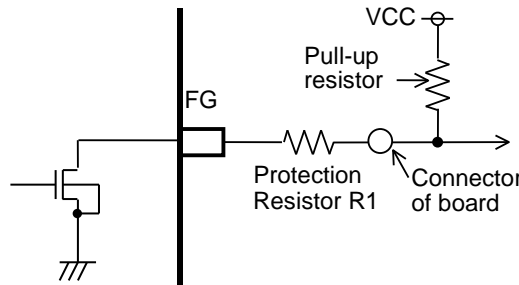
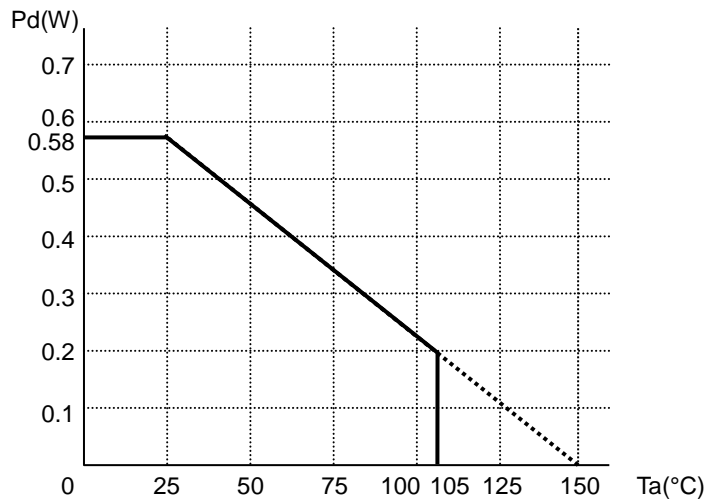


Figure 21. Protection of FG Pin

Thermal Derating Curve

Thermal derating curve indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance θ_{ja} .

Thermal resistance θ_{ja} depends on chip size, power consumption, package ambient temperature, packaging condition, wind velocity, etc., even when the same package is used. Thermal derating curve indicates a reference value measured at a specified condition. Figure 22 shows a thermal derating curve.



* Reduce by 4.68 mW/°C over 25°C.
(70.0mm x 70.0mm x 1.6mm glass epoxy board)

Figure 22. Thermal Derating Curve

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition. However, pins that drive inductive loads (e.g. motor driver outputs, DC-DC converter outputs) may inevitably go below ground due to back EMF or electromotive force. In such cases, the user should make sure that such voltages going below ground will not cause the IC and the system to malfunction by examining carefully all relevant factors and conditions such as motor characteristics, supply voltage, operating frequency and PCB wiring to name a few.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

Operational Notes – continued

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When $GND > Pin A$ and $GND > Pin B$, the P-N junction operates as a parasitic diode.
When $GND > Pin B$, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

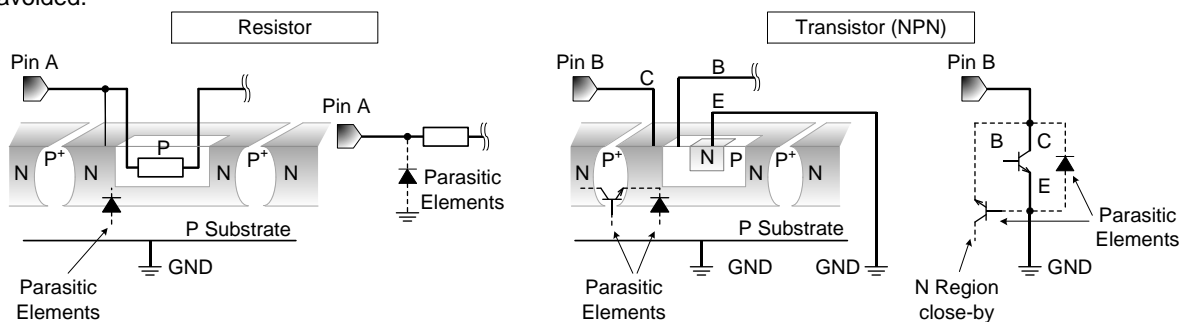


Figure 23. Example of monolithic IC structure

13. Ceramic Capacitor

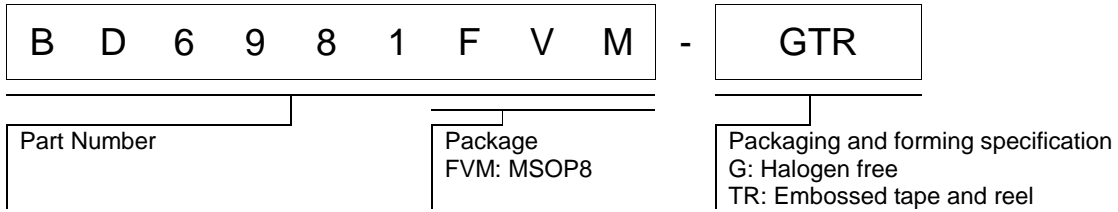
When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

14. Thermal Shutdown Circuit(TSD)

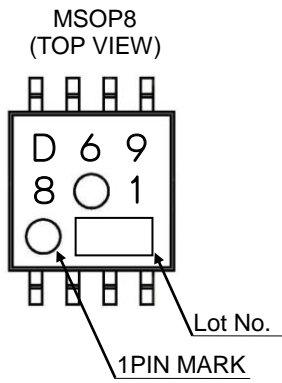
This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's power dissipation rating. If however the rating is exceeded for a continued period, the junction temperature (T_j) will rise which will activate the TSD circuit that will turn OFF all output pins. When the T_j falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

Ordering Information

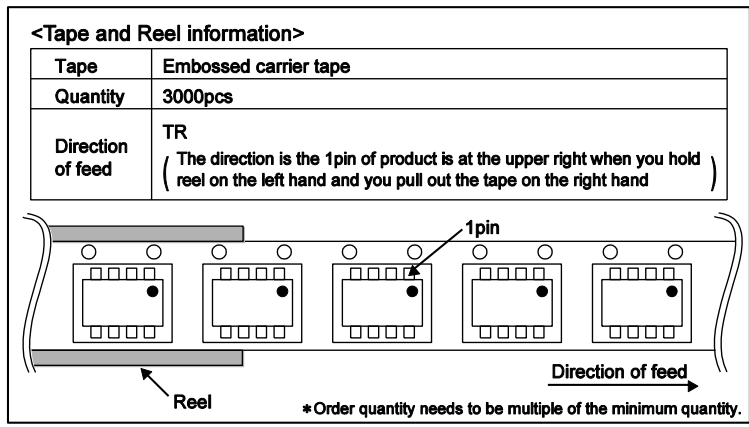
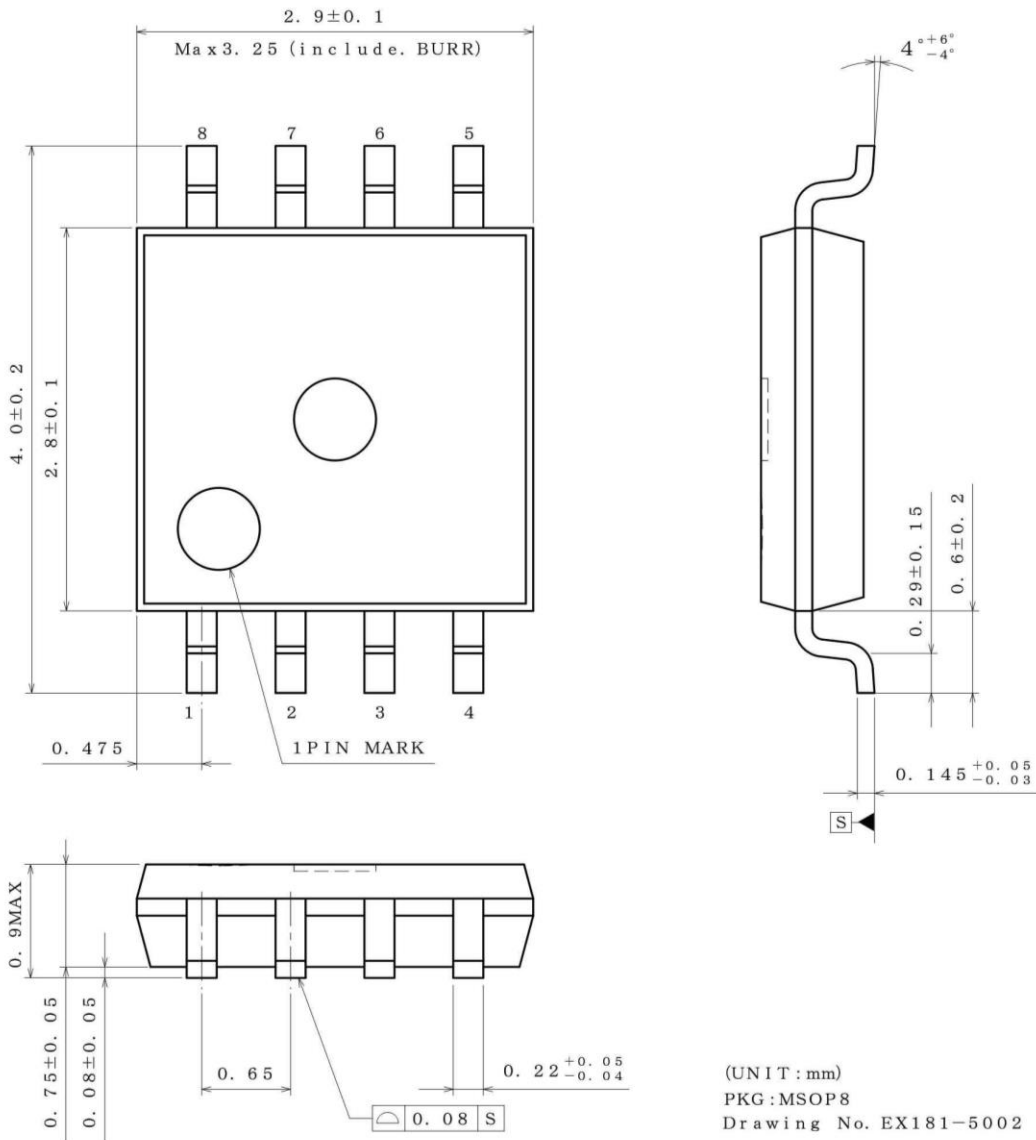


Marking Diagram



Physical Dimension, Tape and Reel Information

Package Name	MSOP8
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JAPAN	USA	EU	CHINA
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CLASS IV		CLASS III	

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 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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